

BB02-GP-A:- 2.00mm x 2.00mm (0.079" x 0.079") ELEVATED FEMALE HEADER, DUAL ROW, 04 TO 80 CONTACTS

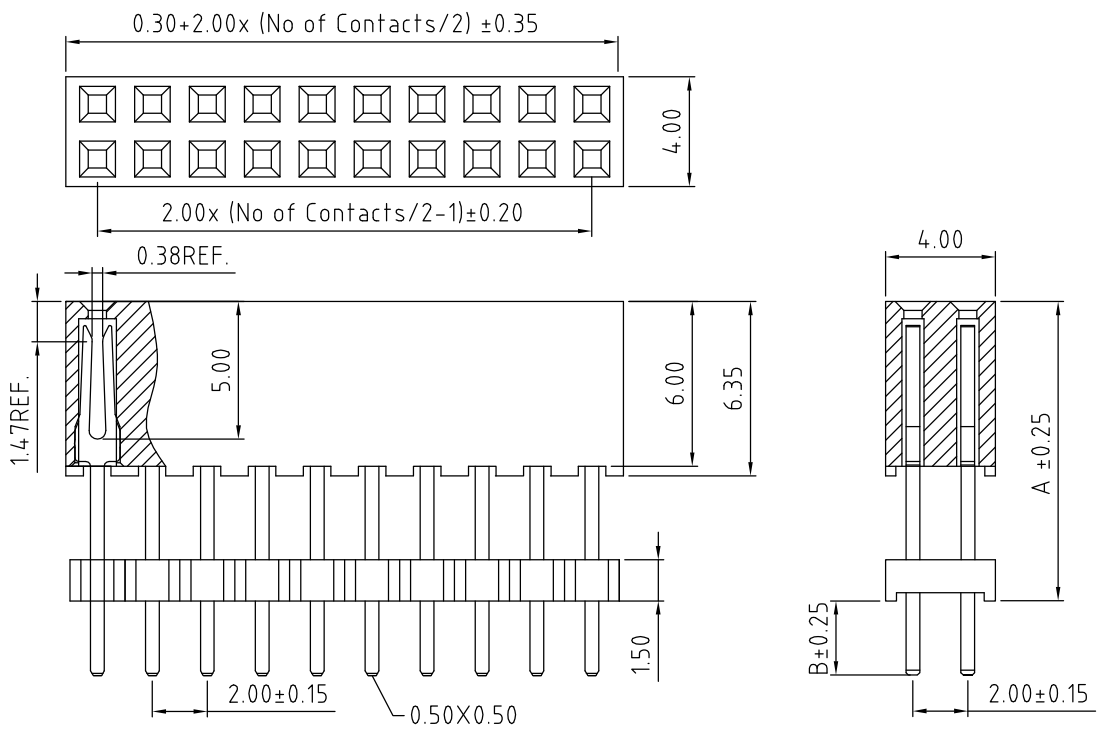
SPECIFICATIONS :

CURRENT RATING	2 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	AC 500 V
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0
	STANDARD: LCP
PLATING	GOLD, TIN, OR SELECTIVE OVER 30~50U" NICKEL
SOLDERABILITY	IR REFLOW: 280°C FOR 10 SEC
	WAVE: 250°C FOR 5-10 SEC
	MANUAL SOLDER: 380°C FOR 3-5 SEC

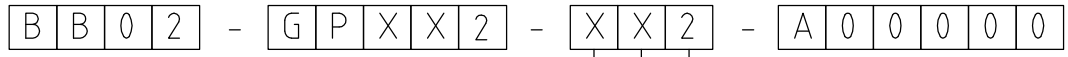
NOTES:

1. RECOMMENDED MATING PIN LENGTH: 3.0MM-4.0MM

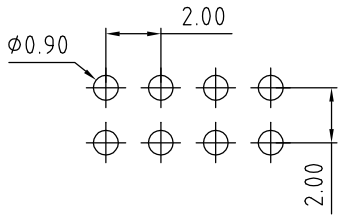
- MATES WITH: -
- | | | |
|---------|---------|---------|
| BB02-FA | BB02-FU | BB02-RN |
| BB02-FD | BB02-FW | BB02-4F |
| BB02-FE | BB02-FY | |
| BB02-FG | BB02-FZ | |
| BB02-FS | BB02-RH | |



HOW TO ORDER



- NO. OF CONTACTS: 04 TO 80
- CONTACT PLATING OPTIONS:
- K = GOLD FLASH (STANDARD)
 - A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 - B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 - C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
 - T = BRIGHT TIN
 - M = MATT TIN
 - D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL
 - E = 10U" GOLD ON CONTACT/BRIGHT TIN ON TAIL
 - F = 15U" GOLD ON CONTACT/BRIGHT TIN ON TAIL
 - G = 30U" GOLD ON CONTACT/BRIGHT TIN ON TAIL
- PROFILE OPTIONS:
- 1 = A : 10.90, B : 2.70
 - 2 = A : 11.39, B : 2.21
 - 3 = A : 8.25, B : 6.00
 - 4 = A : 8.35, B : 5.50
 - 5 = A : 15.50, B : 6.10
 - 6 = A : 12.45, B : 9.15
 - 7 = A : 18.55, B : 3.05
 - 8 = A : 17.70, B : 2.30
 - 9 = A : 14.00, B : 7.60
- PACKAGING OPTIONS:
- 2 = TRAY OR BOX



RECOMMENDED PCB LAYOUT
(TOLERANCE: ±0.05)